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SERIAL NO. 09/766,798

INFORMATION DISCLOSURE CITATION

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APPLICANT: JAMIN LING ET AL.

FILING DATE 01/22/2001

GROUP 2816

U.S. PATENT DOCUMENTS

EXAMINER'S INITIALS	EXHIBIT NUMBER	DOCUMENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
TTN		4,808,769	02/28/89	Nakano et al.			
TTN		4,857,671	08/15/89	Nakano et al.			
TTN		4,970,571	11/13/90	Yamakawa et al.			
TTN		5,212,138	05/18/93	Krulik et al.			
TTN		5,291,374	03/01/94	Hirata et al.			
TTN		5,380,560	01/10/95	Kaja et al.			
TTN		5,747,881	05/05/98	Hosomi et al.			
TTN		5,821,627	10/13/98	Mori et al.			
TTN		5,906,312	05/25/99	Zakel et al.			
TTN		6,040,239	03/21/00	Akram et al.			
TTN		6,049,130	04/11/00	Hosomi et al.			
TTN		6,077,723	06/20/00	Farnworth et al.			
TTN		6,091,252	07/18/00	Akram et al.			
TTN		6,094,058	07/25/00	Hembree et al.			

FOREIGN PATENT DOCUMENTS

EXAMINER'S INITIALS	EXHIBIT NUMBER	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO
TTN		JP411140658A	03/28/99	Japan				

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

	1	Strandjord, A., et al., Break Through Developments in Electroless Nickel/Gold Plating on Copper Based Semiconductors, Int. Symp. Adv. Pkg. Mat. 2000, pp. 107.
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EXAMINER

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*EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to Applicant

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TTN		6,097,087	08/01/00	Farnworth et al.			

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							YES	NO

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

	2✓	Jang, J.W., et al., Crystallization of Electroless Ni-P Under Bump Metallization Induced by Solder Reaction, Int. Symp. Adv. Pkg. Mat. 1999, pp. 252.
	3✓	Stepniak, F., Solder Flip Chips Employing Electroless Nickel: An Evaluation of Reliability and Cost, Inter. PACK 1997.
	4✓	Ostmann, A., et al., Electroless Metal Deposition for Back-End Wafer Processes, Advancing Microelectronics, p. 23.
	5✓	Ulrich, R., et al., Thermosonic Gold Wirebonding to Electrolessly-Metallized Copper Bondpads over Benzocyclobutene, Int. Conf. High Density Pkg. and MCMs 1999, pp. 260.
	6	O'Sullivan, E., et al., Electrolessly deposited diffusion barriers for microelectronics, IBM J.R.&D., Vol. 42, No. 5 - Electrochemical microfabrication.
	7	HBS Technical Proposal #990505-2.OSH, "HBS Mark II Automatic Electroless Nickel/Immersion Gold Plate Tool," dated May 1999

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